

ABSTRACT

An information processing apparatus (5) includes: an information acquisition section (500) configured to acquire polishing conditions including top-ring state information, polishing-table state information, and polishing-fluid-supply-nozzle state information in the chemical mechanical polishing in chemical mechanical polishing of a substrate performed by a substrate processing apparatus including a polishing table configured to rotatably support a polishing pad, a top ring configured to press the substrate against the polishing pad, and a polishing-fluid supply nozzle configured to supply a polishing fluid onto the polishing pad; and a state prediction section (501) configured to predict substrate state information for the substrate on which the chemical mechanical polishing is performed under the polishing conditions by inputting the polishing conditions acquired by the information acquisition section (500) to a learning model (10A) having been generated by machine learning that causes the learning model (10A) to learn a correlation between the polishing conditions and the substrate state information indicating a state of the substrate on which the chemical mechanical polishing is performed under the polishing conditions.

FIG. 13